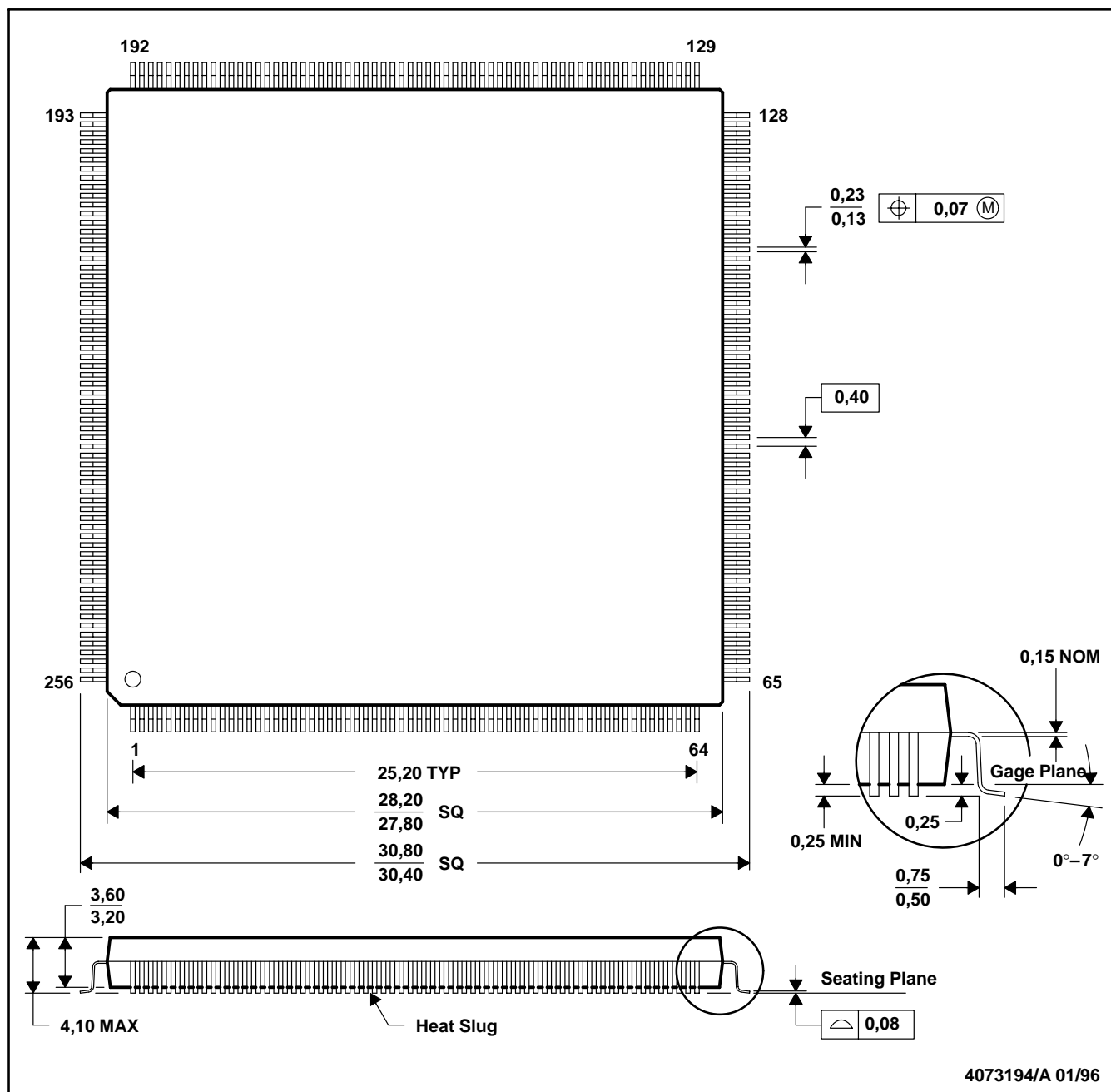


## PBX (S-PQFP-G256)

## PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MO-143  
 D. Thermally enhanced molded plastic package with a exposed heat slug (HSL) on bottom.

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